

Work flow

Wafer box

Wafers in the box

- Slot 1: wafer SOI
- Slot 2: wafer SOI
- Slot 3: wafer SOI

SOI design, slide 3

- Slot 10: borofloat wafer
- Slot 11: borofloat wafer
- Slot 12: borofloat wafer
- Slot 13: Si wafer + 1um SiO₂
- Slot 14: Si wafer + 1um SiO₂

Borofloat design, slide 4

SOI

Electroplating Au

- 3um

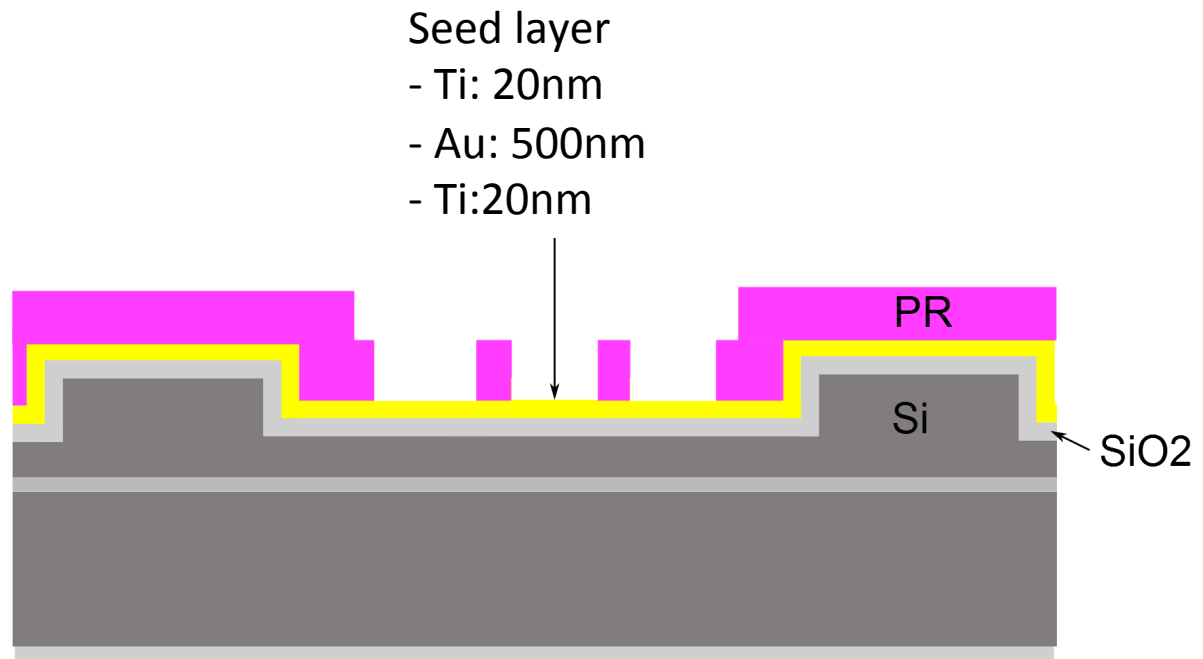
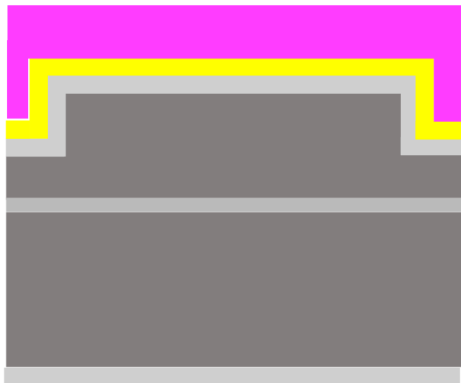
total thickness max (Au) 3.4 um

Dispo: $0.016168 \times 11 \times 8 = 1.422784$

Disc: $13.98 - 6.5 = 7.48$

Total exposed surface: 8.903 cm²

Actual state



Borofloat

Electroplating Au

- 3um

total thickness max (Au) 3.4 um

Dispo: $2.2184 * 11 * 8 = 1.9522$

Cross: 0.0448875

Disc: $13.98 - 6.5 = 7.48$

Total exposed surface: 9.477 cm²

Actual state

